2SB0788 (2SB788)

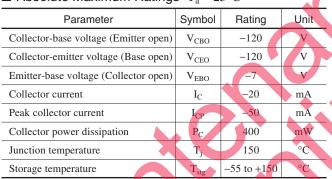
Silicon PNP epitaxial planar type

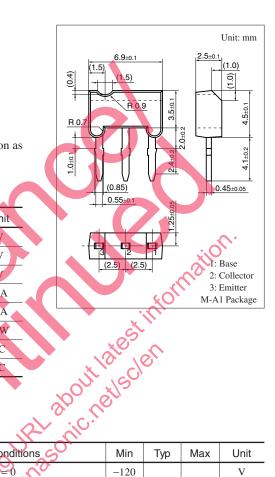
For high breakdown voltage low-noise amplification Complementary to 2SD0958 (2SD958)

Features

- High collector-emitter voltage (Base open) V_{CEO}
- Low noise voltage NV
- M type package allowing easy automatic and manual insertion as well as stand-alone fixing to the printed circuit board.

Absolute Maximum Ratings $T_a = 25^{\circ}C$





Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

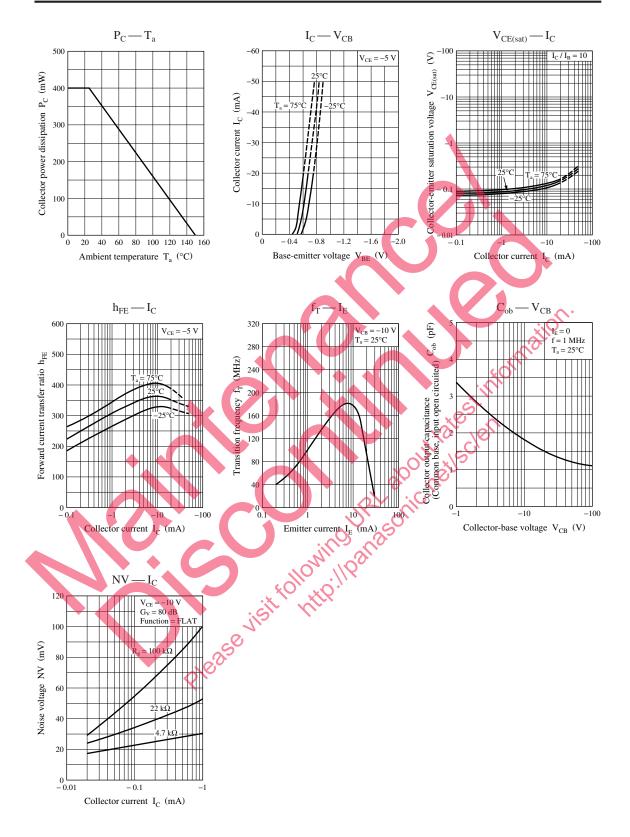
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = -10 \ \mu A, I_{\rm E} = 0$	-120			V
Collector-emitter voltage (Base open)	VCEO	$I_{\rm C} = -1$ mA, $I_{\rm B} = 0$	-120			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm H} = 10 \ \mu \text{A}$ $I_{\rm C} = 0$	-7			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = -50$ V, $I_E = 0$			-100	nA
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = -50 \text{ V}, \text{ I}_{B} = 0$			-1	μΑ
Forward current transfer ratio *	D _{EE}	$V_{CE} = -2 V, I_C = -2 A$	180		520	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -20$ mA, $I_{\rm B} = -2$ mA			- 0.6	V
Noise voltage	NV	$V_{CE} = -40 \text{ V}, I_C = -1 \text{ mA}, G_V = 80 \text{ dB}$			150	mV
		$R_g = 100 \text{ k}\Omega$, Function = FLAT				

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors. 2. *: Rank classification

Rank	Q	R
h _{FE}	180 to 360	260 to 520

Note) The part number in the parenthesis shows conventional part number.

Panasonic



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